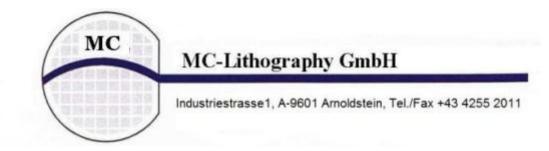


# MC-Lithography GmbH Coater Developer

# Concept



A Product Family Modular Design Variable Process Components Smallest Clean room Footprint Standardized Interfaces



# Advantage

-

#### Lower Cost of Ownership

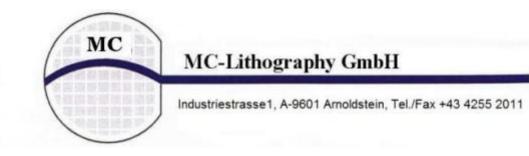
- 80% Common Parts
- Smallest Clean-room Footprint
- High Throughput
- Lower Maintenance Costs

#### **Variable Process Components**

- Modular Design
- Wide range of Applications supported
- Custom Solutions based on Standard Products

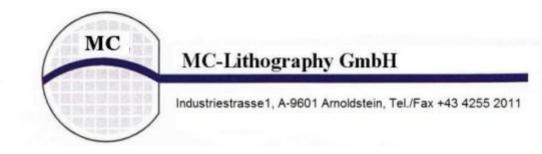
### Standardized Interfaces, open and expandable

- Operator GUI
- Recipe Management
- Automation



## **Cost Of Ownership**

- Smallest Clean-room Footprint in the Industry (Sample 1400x1400)
- High Throughput
- Less Setup Time through distributed Product Files to Multiple Tools
- Lower Maintenance Cost
- Uptime >98%, MTBF >1000h, MTBA >250h, MTTR <2.5h
- 6 Month Preventive Maintenance Intervals
- Less Downtime for Cleaning (*i.e. Process Bowls can be removed w/o tools*)



#### **Wafer Handling**

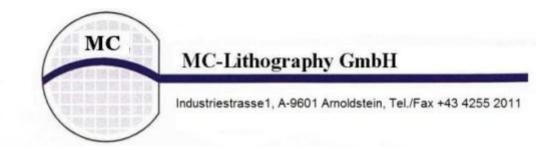
Isel/Genmark, 3-link robot optimized for thin wafer handling Wide range of end-effectors available *(i.e. ceramic, thin-wafer, edge grip...)* Direct control of handling parameter via recipe

#### **Dispense System**

Excellent, repeatable Process Results High-End Components from *Panasonic, SMC, Isel, Beckhoff, CKD, Matrix* Designed for current and future process requirements

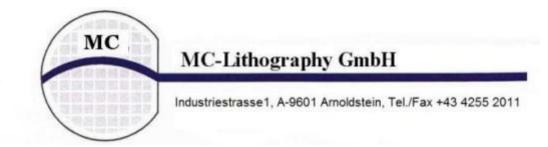
- Linear Positioning Systems
- Progr. & Motor Controlled
- Offset Calibration
- Accuracy: +/- 50μm XYZ

- Up to 4 Dispense Nozzles
- Nozzle pickup through recipe
- Parked in Solvent-bath
- Dummy & Pre-Dispense
- Scan & Multi-Position Dispense

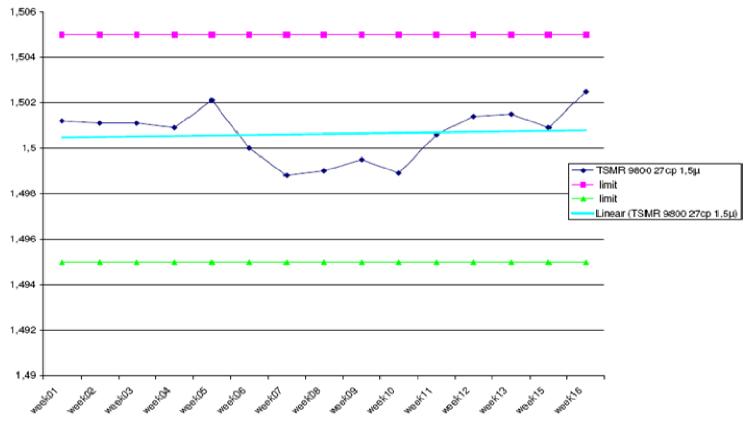


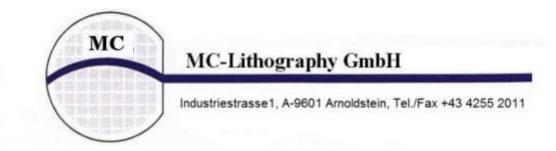
#### **Temperature Modules**

- Module Stack for best form factor
- Excellent uniformity and repeatability
- Wide temperature range available (15°C-65°C, 65°C-180°C, 65°C-450°C)
- Distance control via fixed proximity, prog. proximity or contact
- Hot-Swap' of modules for reduced downtime



**Tool Stability** 

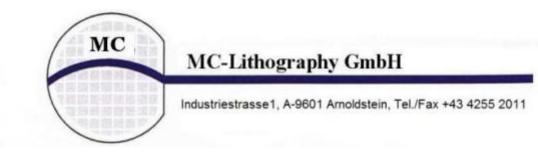




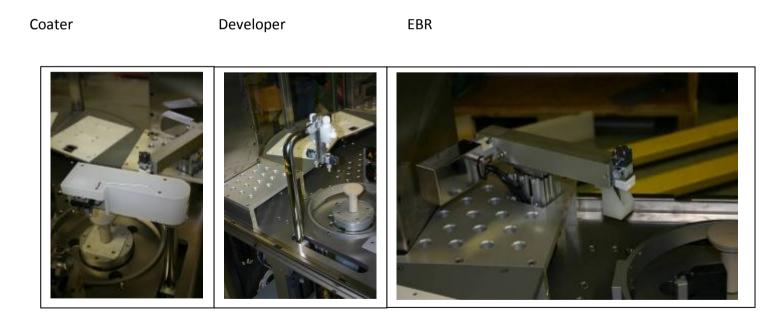
# Picutres

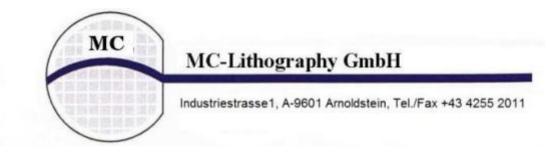
## **Electronic Racks**



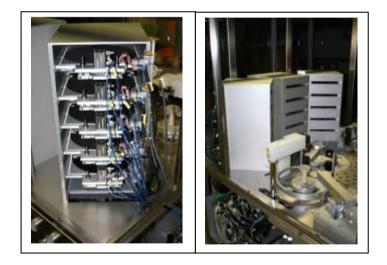


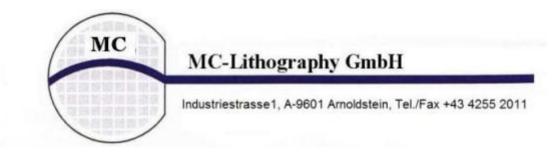
# **Dispense** Arms





# **Hoplates/Coolplates**





# Main Tool/Media Cabinett

